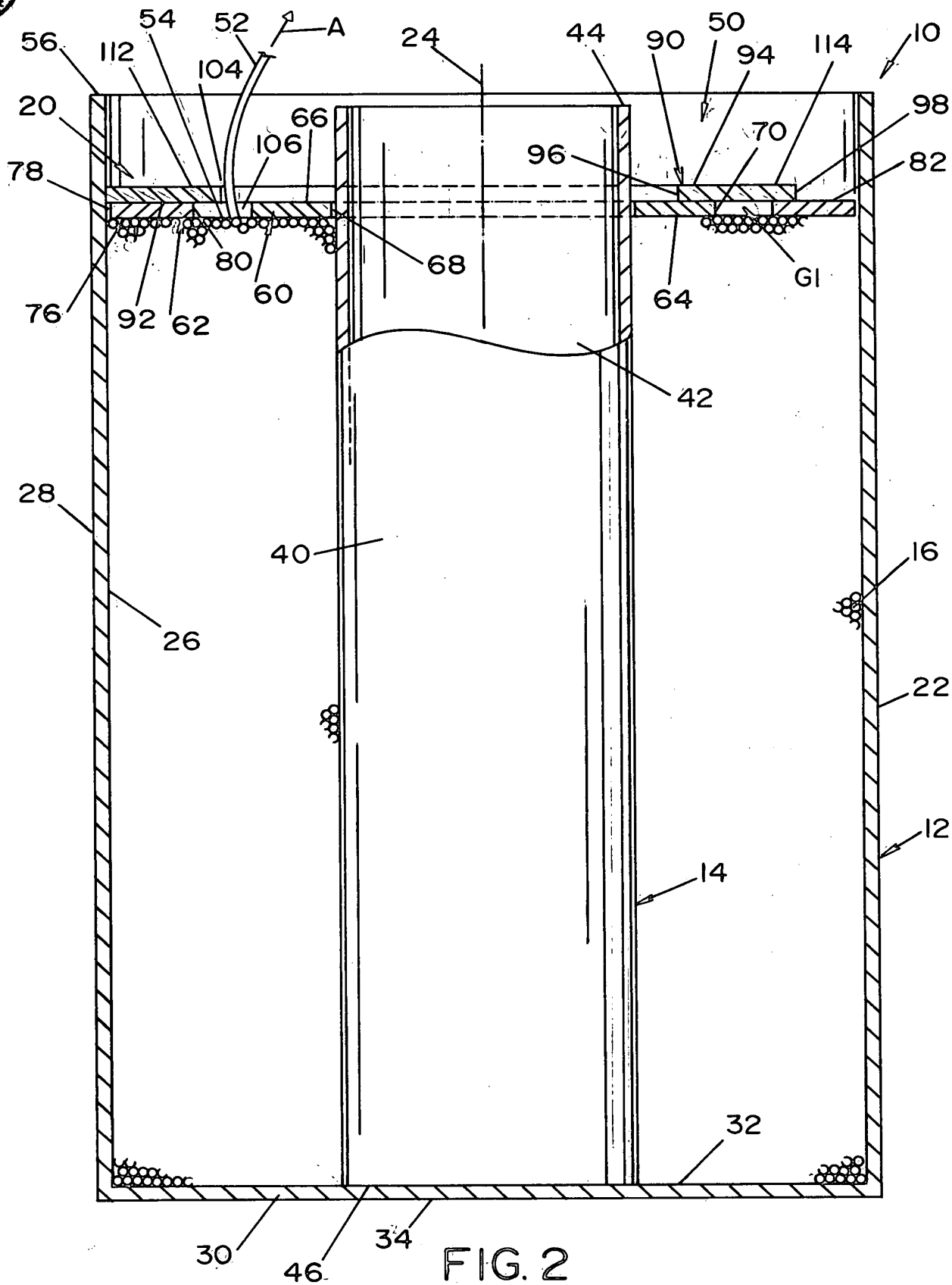


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FIG. 1



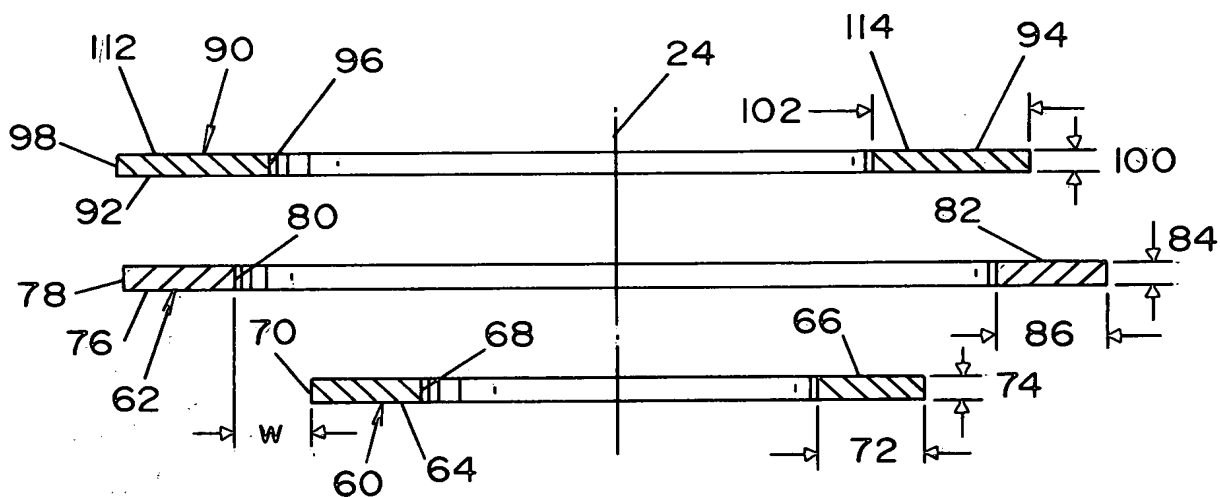
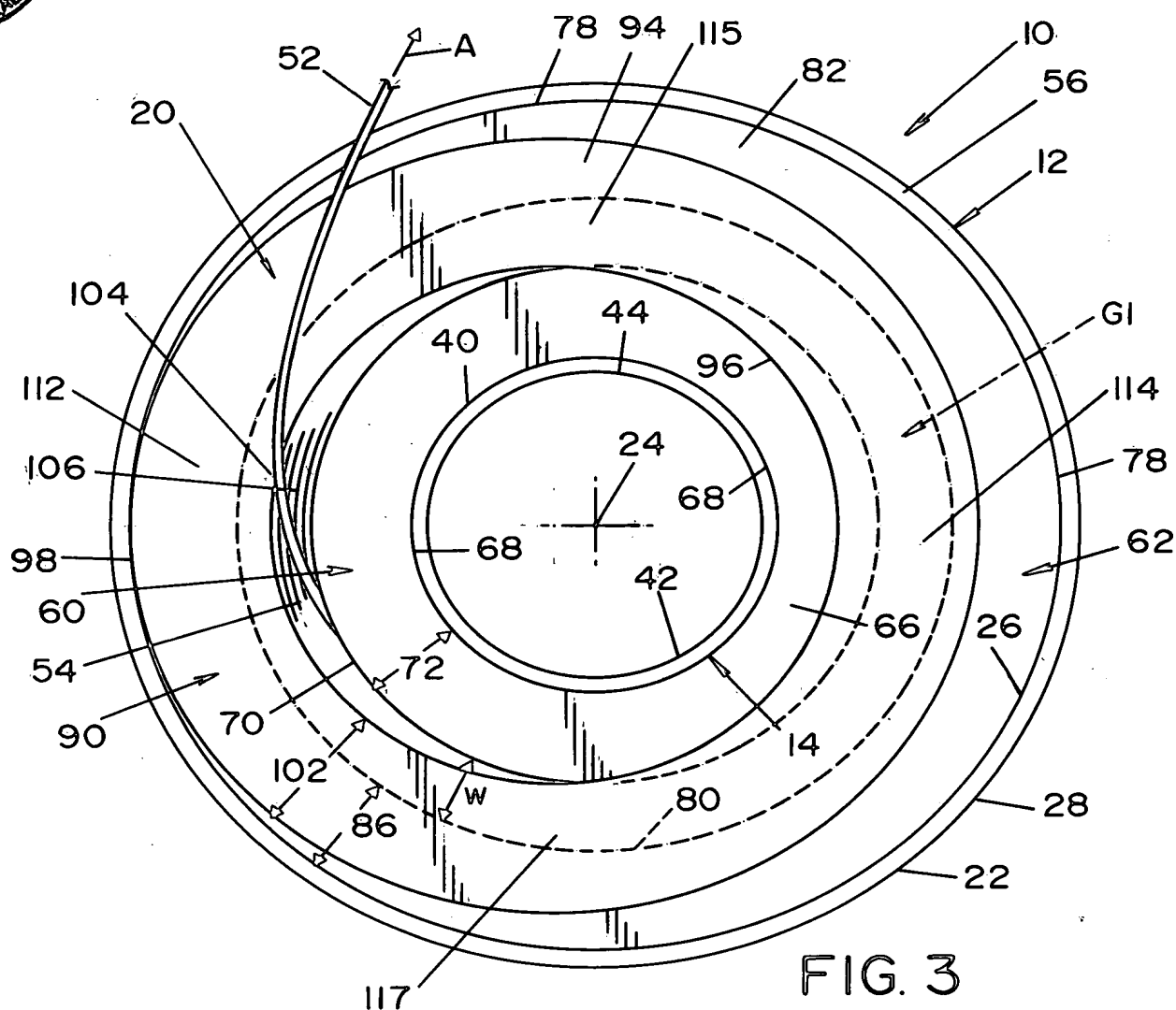
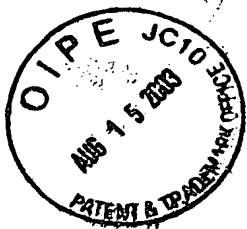


FIG. 2A

FIG. 5 is a cross-sectional view of a multi-layered structure, possibly a semiconductor device or a composite material. The structure consists of several layers and components, labeled with reference numerals:

- 150**: A top layer or substrate.
- 182**: A layer or region within the top section.
- 162**: A layer or region within the top section.
- 52**: A curved line or boundary within the top section.
- 184**: A layer or region within the top section.
- 24**: A vertical line or boundary within the top section.
- 174**: A layer or region within the top section.
- 14**: A layer or region within the top section.
- 176**: A layer or region within the top section.
- 54**: A layer or region within the top section.
- 22**: A layer or region within the top section.
- 172**: A layer or region within the top section.
- 156**: A layer or region within the top section.
- 186**: A layer or region within the top section.
- 164**: A layer or region within the top section.
- 170**: A layer or region within the top section.
- 160**: A layer or region within the top section.
- 158**: A layer or region within the top section.
- G2**: A layer or region within the top section.
- 180**: A layer or region within the top section.
- G2**: A layer or region within the top section.
- 158**: A layer or region within the top section.
- 152**: A layer or region within the top section.
- 40**: A layer or region within the top section.
- 26**: A layer or region within the top section.

The diagram shows a complex arrangement of layers and regions, with some areas containing small circles or dots, possibly representing a specific material or structure. The labels are distributed across the diagram, indicating the location of each component.

